

Registration List: 802.16 Session #10: 6-9 November, 2000

1. *A. Roger Hammons, Jr., Hughes Network Systems, USA
2. *Adrian Boyer, Wi-LAN Inc., CANADA
3. *Adrian Florea, Alcatel, CANADA
4. *Amos Dotan, WaveIP Ltd., ISRAEL
5. *Anader Benyamin-Seeyar, Harris Corporation, CANADA
6. *Andrew Middleton, Airspan Communications Ltd., UK
7. *Andy McGregor, Nortel Networks, CANADA
8. Andy Schiltz, Ensemble Communications Inc., USA
9. Anish Tolia, Oren Semiconductor, USA
10. *Anton Monk, Tioga Technologies, USA
11. *Apurva Mody, Georgia Institute of Technology, USA
12. Arnult Simmou, C-Bridge, USA
13. Arthur Wang, WirelessHome, USA
14. *Arun Arunachalam, Conexant Systems, Inc., USA
15. *Avraham Freedman, Hexagon System Engineering, ISRAEL
16. *Bakri Aboukarr, Alcatel, CANADA
17. *Barry Lewis, Radiocommunications Agency, UK
18. *Baruch Buskila, WaveIP Ltd., ISRAEL
19. *Baruch Halachmi, RADWIN Ltd., ISRAEL
20. *Baya Hatim, Wireless Facilities, Inc., USA
21. *Behshad Baseghi, Malibu Networks, USA
22. *Bill Steagall, L3 Communications, USA
23. *Bob Heise, Wi-LAN Inc., USA
24. *Bob Malkemes, Sarnoff Corporation, USA
25. *Brandon Hinton, Winstar Communications, USA
26. Brett Bernath, Tioga Technologies, USA
27. *Brian Eidson, Conexant Systems, Inc., USA
28. *Brian Kiernan, InterDigital Communications Corp., USA
29. *Bruce Currivan, Broadcom Corp., USA
30. Burhan Masood, SMSC, USA
31. *Byung-Jae Kwak, Samsung Electronics Co., Ltd., KOREA
32. *C.R. (Rick) Baugh, Harris Communications, Inc., USA
33. *Carl Bushue, Sprint, USA
34. *Carl Eklund, Nokia Research Center, FINLAND
35. *Carl Scarpa, Hitachi America R&D, USA
36. Carl Andren, Intersil Corporation, USA
37. *Carlos Belfiore, DMC Stratex Networks, Inc., USA
38. *Chaim Shenhav, nBand Communications, USA
39. *Chaoming Zeng, DMC Stratex Networks, Inc., USA
40. *Charles Farlow, ADC Telecommunications, USA
41. Cherif Chibane, Sony, USA
42. *Chet Shirali, Vvyo Inc., USA
43. *Chris Cant, Telegen Ltd. (Floware Ltd.), UK
44. *Chris Tappenden, Nortel Networks, CANADA
45. *Clement Tse, Tality, LP., USA
46. Coleman Hum, Alcatel, CANADA
47. *Dale Hancock, RF Magic, Inc., USA
48. *David Chauncey, Clearwire Technologies, USA
49. *David Husson, Widax Corp, USA
50. *David Trinkwon, Transcomm Inc, USA
51. *David Williams, Advanced Hardware Architectures, USA

52. *Dean Chang, Aperto Networks, USA
53. *Demosthenes Kostas, Adaptive Broadband Inc., USA
54. *Drayt Avera, RF Solutions, USA
55. *Durga Satapathy, Sprint, USA
56. Edward Doherty, Coreon Inc., USA
57. *Eli Avivi, WaveIP Ltd., ISRAEL
58. *Eric Hall, L3 Communications, USA
59. *Eric Jacobsen, Intel Corp., USA
60. *Erol Yurtkuran, Integrity Broadband Networks, Inc., USA
61. *Eung-Bae Kim, ETRI (Electronics Telecomm. Research Institute), KOREA
62. *G. Jack Garrison, Harris Corporation, USA
63. *Gene Robinson, E. A. Robinson Consulting, Inc., USA
64. *George Fishel, Communications Consulting Services, USA
65. *George Stamatelos, Nortel Networks, CANADA
66. *Glen Sater, Motorola Inc., USA
67. *Guy Lopez, Harris Corporation, USA
68. *Guy Resheff, Turbotech Inc., ISRAEL
69. *Hamadi Jamali, Canon R&D Center Americas, Inc., USA
70. *Heinz Lycklama, Siros Networks, USA
71. *Hesham El Gamal, Hughes Network Systems, USA
72. *Hesham El-Damhougy, Western Multiplex, US
73. *Hikmet Sari, Pacific Broadband, USA
74. Hiroki Sugimoto, Oki Techno Centre (Singapore) Pte Ltd, SINGAPORE
75. *Huanchun Ye, Radix Wireless, Inc., USA
76. *Ian Baragar, Nortel Networks, CANADA
77. *Inchul Kang, Malibu Networks, USA
78. *Itzik Kitroser, Runcom Technologies Ltd., ISRAEL
79. J. Leland Langston, Crossspan Network Access Technologies, USA
80. *J. Scott Marin, Motorola, Inc., USA
81. *Jacob Jorgensen, Malibu Networks, USA
82. *James Cornelius, MSI, USA
83. *James Mollenauer, Technical Strategy Associates, USA
84. James Brennan, linuxfreak, USA
85. *Jason Krasnow, Solectek Corporation, USA
86. *Jay Klein, Ensemble Communications Inc., USA
87. *Jay Ramasastry, WinStar Communications, Inc., USA
88. Jean-Pierre Devieux, Conexant, USA
89. Jeff Jan, Maples Communications Inc., USA
90. Jeffrey Foerster, Intel Corp., USA
91. *Jim Simkins, Xilinx, USA
92. *John Finklea, Signal Technology Corporation, USA
93. *John Kim, Georgia Institute of Technology, U.S.A.
94. *John Langley, Com21, Inc., USA
95. *John Liebetreu, SiCOM, Inc., USA
96. *John Sydor, Industry Canada/Communications Research Centre, CANADA
97. John Wiss, nBand Communications, USA
98. *Jon Shields, Solectek Corporation, USA
99. *Jori Arrakoski, Nokia Research Center, FINLAND
100. *Jose Tellado, iospan wireless, USA
101. *JosŽ Costa, Nortel Networks, CANADA
102. *Joseph Hakim, Aperto Networks, USA
103. *Juan Carlos Zuniga, Harris Corporation, CANADA
104. *Jun Shen, Aperto Networks, USA
105. K.V.S Hari, Stanford University, USA

106. *Karl Stambaugh, Motorola Inc., USA
107. *Kaushik Barman, Silicon Automation Systems, USA
108. *Ken Peirce, Malibu Networks, USA
109. *Ken Singleton, Barcombe Associates (UK), USA
110. *Ken Stanwood, Ensemble Communications Inc., USA
111. Ken Biba, The Value Group, USA
112. *Kobi Blechman, Ceragon Networks, USA
113. Kwang-Cheng Chen, IPC Taiwan Laboratories, USA
114. *Lars Lindh, Nokia Research Center, FINLAND
115. *Lei Wang, Wi-LAN Inc., CANADA
116. *Luc Boucher, Industry Canada, CANADA
117. *Malcolm Sellars, Adaptive Broadband, UK
118. *Malik Audeh, Hybrid Networks, Inc., USA
119. *Marianna Goldhammer, BreezeCOM Ltd., ISRAEL
120. *Mark Foley, RF Magic, Inc., USA
121. *Mark Vogel, 3Com Corp., USA
122. *Mary Condie, Alcatel, CANADA
123. Matthias Kindler, Infineon Technologies, USA
124. *Menashe Shahar, Vyyo Ltd., ISRAEL
125. *Michael Donahue, Western Multiplex, USA
126. *Michael Hamilton, WinNet MCS/Innowave, USA
127. *Michael Stewart, Escape Communications, USA
128. *Mike Patullo, SpaceBridge Networks Corp., USA
129. *Mike Rude, ADC Telecommunications, USA
130. *Minfei Leng, Clearwire Technologies, USA
131. *Mohammed Ashtjou, WinNet, USA
132. *Moritz Harteneck, Infineon Technologies, USA
133. *Moshe Ran, TelesciCOM Ltd., ISRAEL
134. *Muya Wachira, Nortel Networks, CANADA
135. *Naftali Chayat, BreezeCOM Ltd., ISRAEL
136. *Namil Kim, ETRI, KOREA
137. *Nico Van Waes, Nokia Networks, USA
138. *Oliver Seller, sacet, USA
139. *P.G. Poonacha, Silicon Automation Systems, USA
140. *Paul Struhsaker, Raze Technologies, USA
141. *Paul Thompson, Paul Thompson Associates, USA
142. Paul Nikolich, ADC Telecommunications, USA
143. *Philip Orlik, Mitsubishi Electric Research Laboratory, USA
144. *Philip Whitehead, Radiant Networks PLC, UK
145. Phillip Gee, Wi-LAN Inc., CANADA
146. Piyush Sodha, WirelessHome, USA
147. *Rakesh Gupta, Alcatel, CANADA
148. Rama Mwikalo, Virata, USA
149. *Randall Schwartz, Radix Wireless, Inc., USA
150. *Raymond Thomas, Lucent Technologies, USA
151. *RŽmi Chayer, Harris Corporation, CANADA
152. *Radu Selea, Redline Communications, USA
153. *Reza Arefi, Wireless Facilities, Inc., USA
154. Ritesh Vishwakarama, Telencomm, USA
155. *Robert Foster, Wavtrace, Inc., USA
156. *Robert Ward, SciCom, USA
157. *Robert Whiting, Gabriel Electronics, USA
158. Robert Roy, Mobilian, USA
159. *Roderick McMullin, DragonWave Inc., CANADA

160. *Roger Durand, Cabletron Systems, USA
161. *Roger Marks, NIST, USA
162. *Ron McCallister, SiCOM, Inc., USA
163. *Ron Nadiv, Ceragon Networks, ISRAEL
164. *Ronald Coles, DMC Stratex Networks, Inc., USA
165. *Ronald Meyer, Crosspan Network Access Technologies, USA
166. *Russell McKown, Raze Technologies, USA
167. Sanjay Moghe, RF Solutions, USA
168. *Sean Sonander, Advanced Hardware Achitectures, USA
169. *Sergio Licardie, DMC Stratex Networks, Inc., USA
170. Shawn McCann, Agilent Technologies, USA
171. Simon Widdowson, Lucent Technologies, USA
172. *Song An, CommAccess Technologies, Inc., USA
173. *Srinath Hosur, Texas Instruments, Inc., USA
174. *Srinivas Lingam, nBand Communications, USA
175. *Stanley Reible, Oak Wireless, USA
176. Stephen Oh, Lucent Technologies, USA
177. *Steven Smith, Intersil Corporation, USA
178. *Subir Varma, Aperto Networks, USA
179. Takuro Sato, Waseda University, USA
180. *Tal Kaitz, BreezeCOM Ltd., USA
181. *Thierry Derand, Mitsubishi Electric, USA
182. *Thomas Kolze, Broadcom Corp., USA
183. *Tie-Jun Shan, Lucent Technologies, USA
184. *Titus Lo, AT&T Wireless Group, USA
185. *Todd Taylor, WirelessHome, USA
186. Toshibiko Kawai, Sony, USA
187. *Uzi Padan, InnoWave ECI Wireless Systems Ltd., ISRAEL
188. *Vacit Arat, TelesciCOM Ltd., USA
189. *Vaia Sdralia, University of Sheffield, USA
190. *Valentine Rhodes, Intel Corporation, USA
191. Vic Hayes, Lucent Technologies, NETHERLANDS
192. *Vicente Quilez, Alcatel Spain, SPAIN
193. *Victor Shtrom, iospan wireless, USA
194. *Vinko Erceg, iospan wireless, USA
195. *Vito Scaringi, Alcatel, CANADA
196. *Vlad Mitlin, 3Com Corp., USA
197. *Vladimir Yanover, BreezeCOM Ltd., ISRAEL
198. *Walt Roehr, InterDigital/TNC, USA
199. *Wayne Hunter, Crosspan Network Access Technologies, USA
200. *William Myers, Signal Technology Corp., US
201. William Crilly, Jr., Agilent Technologies, USA
202. William Ralston, L-3 Communications, USA
203. *Willie Lu, Infineon Technologies Corp., USA
204. *Xiaofeng Wang, PMC-Sierra, Inc., CANADA
205. *Yair Bourlas, Ensemble Communications Inc., USA
206. *Yigal Leiba, BreezeCOM Ltd., ISRAEL
207. *Yoav Hebron, Conexant Systems, Inc., USA
208. *Yonatan Manor, Oren Semiconductor Ltd., ISRAEL
209. *Yossi Segal, Runcom Technologies Ltd., ISRAEL
210. Yossi Zilberfarb, COMMPRIZE, USA
211. *Zion Hadad, Runcom Technologies Ltd., ISRAEL

*Met 75% presence requirement for "participation" credit (174 people). Direct questions to [the Secretary](#).

All paid registration fee.

[Return to Session #10 Page](#)